

Development Trends of Hybrid Bonding Technology and Applications in Semiconductors (pre-order)

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Abstracts

As semiconductor chip components continue to shrink and circuit density increases, the size and spacing of signal interconnect electrodes are facing a constant demand for downsizing. This miniaturization trend poses even higher requirements for interconnect bonding technology in chip stacking. Currently, hybrid bonding stands out as the key technology that best meets these demands. This report examines the current development status of hybrid bonding technology, investigates its integration into various application chip packaging by industry players, and explores the future trends in technological advancements and applications.

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